



## Material Content Data Sheet



Sales Product Name	TLE7242-2G			Issued		25. November 2019		
MA#	MA005348333							
Package	PG-DSO-28-42			Weight*		824.63 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	22.000	2.67	2.67	26679	26679
leadframe	inorganic material	phosphorus	7723-14-0	0.069	0.01		83	
	non noble metal	zinc	7440-66-6	0.275	0.03		333	
	non noble metal	iron	7439-89-6	5.500	0.67		6669	
	non noble metal	copper	7440-50-8	223.311	27.08	27.79	270803	277888
wire	non noble metal	copper	7440-50-8	0.426	0.05	0.05	516	516
encapsulation	organic material	carbon black	1333-86-4	1.124	0.14		1363	
	plastics	epoxy resin	-	51.712	6.27		62710	
	inorganic material	silicondioxide	60676-86-0	509.248	61.75	68.16	617552	681625
leadfinish	non noble metal	tin	7440-31-5	4.913	0.60	0.60	5958	5958
plating	noble metal	silver	7440-22-4	1.047	0.13	0.13	1270	1270
glue	plastics	epoxy resin	-	1.250	0.15		1516	
	noble metal	silver	7440-22-4	3.750	0.45	0.60	4548	6064
*deviation	< 10%	Sum in total:			100.00			1000000

### Important Remarks:

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This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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